Roll No.

8717

Printed Pages: 3

BT-7 / M 12 VLSI DESIGN Paper-ECE-401-E

Time allowed: 3 hours] [Maximum marks: 100

Note: Attempt any five questions, selecting at least one from each unit.

Unit-I

- 1. (a) Describe with illustrations, the two-metal n-well CMOS fabrication process to show how a CMOS inverter is fabricated. List all the masks in sequence of usage.
 - (b) Discuss the voltage transfer characteristics of E/D NMOS inverter.
- 2. (a) Derive the drain current equation for a MOS transistor. What is channel length modulation?
- (b) Draw the stick diagram of a 1-bit full adder in E/D NMOS technology.

Unit-II

- 3. (a) Why do we get progation delays? For the CMOS fabrication process with device parameters as: $\mu_n.C_{OX} = 120 \ \mu\text{A/V}^2, \ \mu_p.C_{OX} = 40 \ \mu\text{A/V}^2,$ $L = 0.6 \ \mu\text{m}, \ V_{T0,n} = 0.8 \ V, \ V_{T0,p} = -1.0 \ V,$ $V_{DD} = 3 \ V, \ W_{min} = 1.2 \ \mu\text{m}. \ Design a \ CMOS$ inverter by determining the channel widths $W_n \ \text{and} \ W_p \ \text{of the nMOS and pMOS transistors,}$ to meet the propagation delay times $\tau_{PHL} \leq 0.2$ ns and $\tau_{PLH} \leq 0.15 \ \text{ns. Assuming the output load }$ capacitance of 0.2 pF and ideal step input.
 - (b) What is packaging? Discuss various packaging technologies.
- 4. Comparing the two scaling theories, constant-E and constant-V, show analytically by using equations how the delay time, power dissipation, power density, power-speed product are affected in terms of the scaling factor S. Which theory is more suitable for smaller geometries?

(3)

Unit-III

- 5. What do you understand by routing? Discuss the various routing algorithms. What is the grid model for global routing?
- 6. Discuss the various Partitioning Algorithms. Discuss the advantages and disadvantages of each.

Unit-IV

- 7. Describe the delay models in Physical Design. How are timing constraints applied?
- 8. Write short notes on:
 - (a) Delay models in physical design. 10
 - (b) Timing minimization.